

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph spanning pages 7 and 8 as follows:

In accordance with certain aspects of the present invention, a modified solder bump pattern can be used to fully isolate an unused or non-functional circuit as illustrated in **FIG. 5**. Locations of the circuitry 108, 112, 116 and 120 are again depicted by broken lines and the circuit designation numbers. In this illustration, circuit ~~[[108]] 112~~ is to be effectively disabled by virtue of not connecting the power supply voltage and ground. These connections, along with all other connections in this illustration are omitted by use of a different solder mask than that described in conjunction with **FIG. 4**. The solder mask used to deposit solder to die 100 in **FIG. 5** has no provision for permitting any solder to be applied to interconnect any of the circuitry of circuit ~~[[108]] 112~~. Thus, no power or ground connections are made to circuit ~~[[108]] 112~~ and the circuit is isolated and disabled from the remaining circuitry of die 100. All connections are made to circuit ~~[[112]] 108~~ so that, in the example embodiment, a single microprocessor core ~~[[112]] 108~~ is active in the die soldered according to **FIG. 5**. The substrate used in connection with this solder bump pattern may be identical to that used in connection with **FIG. 4** and incorporate a complete set of solder pads, or may omit the solder pads associated with circuit ~~[[112]] 108~~ without departing from the invention.

Please amend the first full paragraph on page 8 as follows:

FIG. 6 illustrates another exemplary solder bump arrangement in which circuit ~~[[112]] 108~~ is disabled and circuit ~~[[108]] 112~~ is enabled. Again, locations of the circuitry 108, 112, 116 and 120 are depicted by broken lines and the circuit designation numbers. In this example, circuit ~~[[112]] 108~~ is disabled using a third solder mask or other mechanism to selectively deposit solder on the die. Thus, in this embodiment, power and other connections are omitted to circuit ~~[[112]] 108~~ to effectively disable the circuit. In this illustration, however, solder pad ~~[[140]] 130~~ is still connected in order to make a stable ground substrate connection over the unused circuit ~~[[112]] 108~~. Again, the substrate used in connection with this solder bump pattern may be identical to that used in connection with **FIG. 4** and incorporate a complete set of solder pads, or may

omit the solder pads associated with circuit ~~[[112]]~~ 108 (except for the ground pad ~~[[140]]~~ 130) without departing from the invention.